



PNP SURFACE MOUNT TRANSISTOR

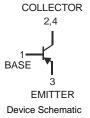
Features

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (DCP68)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green Molding" Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD -202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.112 grams







Top View Pin Out Configuration

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Collector-Base Voltage	V _{CBO}	-25	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Base Voltage	V _{EBO}	-5.0	V
Collector Current	Ic	-1.0	Α
Peak Pulse Current	I _{CM}	-2.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ T _A = 25°C	P _D	1	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ T _A = 25°C	$R_{ heta JA}$	125	°C/W
Power Dissipation (Note 4) @ T _A = 25°C	P _D	2	W
Thermal Resistance, Junction to Ambient Air (Note 4) @ T _A = 25°C	$R_{ heta JA}$	62.5	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Notes:

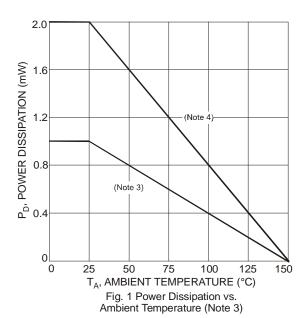
- 1. No purposefully added lead
- 2. Diodes Inc.'s "Green" Policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 4. Device mounted on FR-4 PCB with 1in.2 copper pad layout.

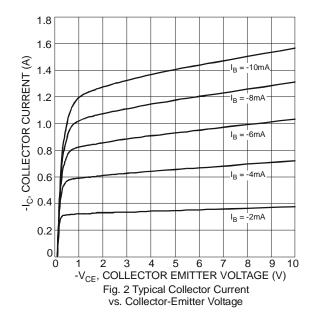


Electrical Characteristics @TA = 25°C unless otherwise specified

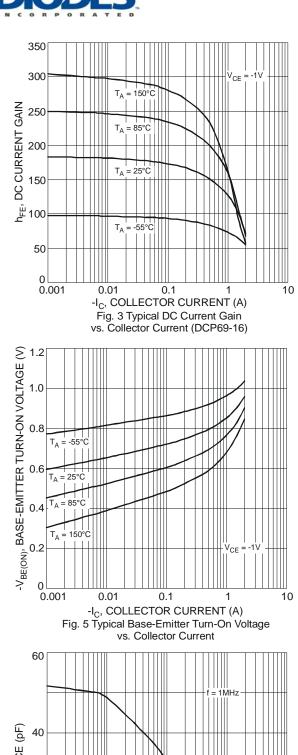
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERI	OFF CHARACTERISTICS						
Collector-Base Brea	kdown Voltage	V _{(BR)CBO}	-25	_	_	V	$I_C = -10\mu A, I_E = 0$
Collector-Emitter Bre	eakdown Voltage (Note 5)	V _{(BR)CEO}	-20	_	_	V	$I_C = -1.0 \text{mA}, I_B = 0$
Emitter-Base Breakd	Emitter-Base Breakdown Voltage		-5.0	_	_	V	$I_E = -10\mu A, I_C = 0$
Collector-Base Cutoff Current		I _{CBO}	_	_	-100 -10	nA μA	$V_{CB} = -25V, I_E = 0$ $V_{CB} = -25V, I_E = 0, T_A = 150$ °C
Emitter-Base Cutoff Current		I _{EBO}	_	_	-100	nA	$V_{EB} = -5.0V, I_{C} = 0$
ON CHARACTERIS	TICS (Note 5)						•
DC Current Gain	DCP69, DCP69-16, DCP69-25	h _{FE}	50 60	_	_	-	$V_{CE} = -10V$, $I_{C} = -5.0$ mA $V_{CE} = -1.0V$, $I_{C} = -1.0$ A
	DCP69		85	_	375		V _{CE} = -1.0V, I _C = -500mA
	DCP69-16		100	_	250		$V_{CE} = -1.0V, I_{C} = -500mA$
	DCP69-25		160	_	375		V _{CE} = -1.0V, I _C = -500mA
Collector-Emitter Saturation Voltage		V _{CE(SAT)}	_	_	-0.5	V	I _C = -1.0A, I _B = -100mA
Base-Emitter Turn-On Voltage		V _{BE} (ON)	_	_	-0.7 -1.0	V	$V_{CE} = -10V$, $I_{C} = -5.0$ mA $V_{CE} = -1.0V$, $I_{C} = -1.0$ A
SMALL SIGNAL CHARACTERISTICS							
Current Gain-Bandwidth Product		f⊤	40	200	_	MHz	$V_{CE} = -5.0V$, $I_{C} = -50mA$, $f = 100MHz$
Output Capacitance		C _{obo}	_	17	_	pF	$V_{CB} = -10V, f = 1 \text{ MHz}$

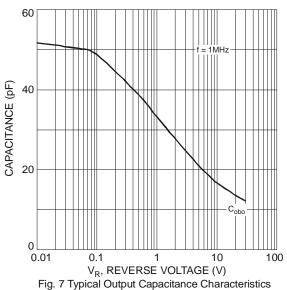
Notes: 5. Measured under pulsed conditions. Pulse width = 300μ S. Duty cycle $\leq 2\%$.

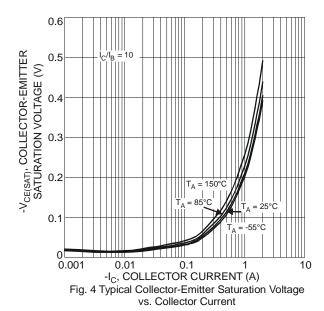


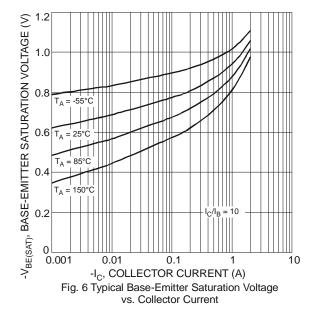


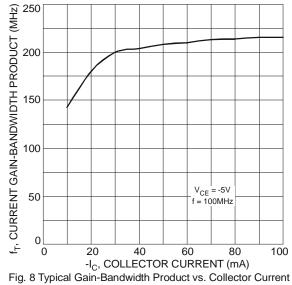












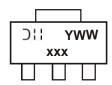


Ordering Information (Note 6)

Part Number	Case	Packaging
DCP69-13	SOT-223	2500/Tape & Reel
DCP69-16-13	SOT-223	2500/Tape & Reel
DCP69-25-13	SOT-223	2500/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

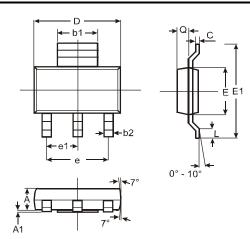
Marking Information



xxx = Product Type Marking Code P12 = DCP69 P12-16 = DCP69-16 P12-25 = DCP69-25 Otto = Manufacturer's code marking

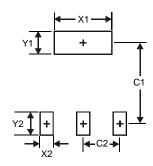
YWW = Date Code Marking Y = Last digit of year (ex: 7 = 2007) WW = Week code 01 - 52

Package Outline Dimensions



SOT-223				
Dim	Min	Max	Тур	
Α	1.55	1.65	1.60	
A1	0.010	0.15	0.05	
b1	2.90	3.10	3.00	
b2	0.60	0.80	0.70	
С	0.20	0.30	0.25	
D	6.45	6.55	6.50	
E	3.45	3.55	3.50	
E1	6.90	7.10	7.00	
е	_	_	4.60	
e1			2.30	
L	0.85	1.05	0.95	
Q	0.84	0.94	0.89	
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3



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